

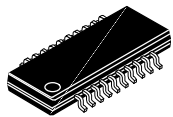
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

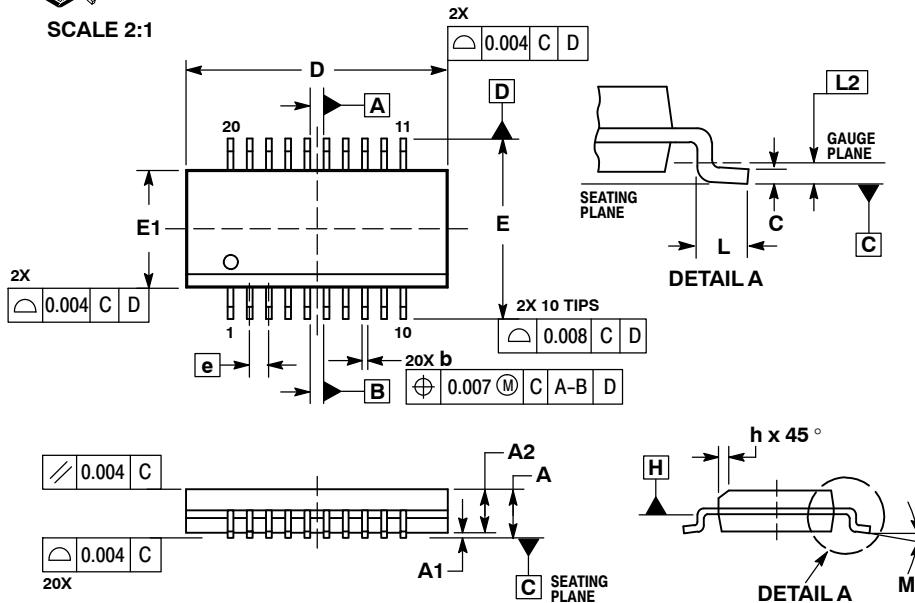


## QSOP20 CASE 492AC-01 ISSUE O

DATE 22 MAR 2011



SCALE 2:1

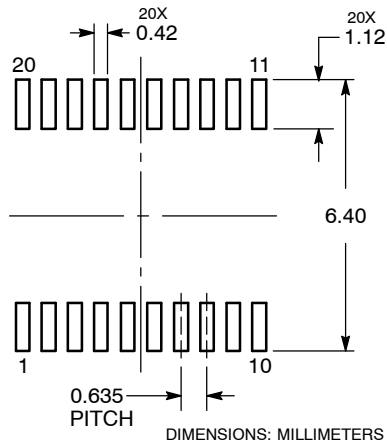


NOTES:

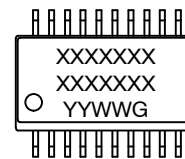
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.005 PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.005 PER SIDE. D AND E1 ARE DETERMINED AT DATUM H.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	----	0.069	----	1.75
A1	0.004	0.010	0.10	0.25
A2	0.049	----	1.24	----
b	0.008	0.012	0.20	0.30
c	0.004	0.010	0.10	0.25
D	0.341 BSC	----	8.66 BSC	----
E	0.236 BSC	----	5.99 BSC	----
E1	0.154 BSC	----	3.91 BSC	----
e	0.025 BSC	----	0.635 BSC	----
h	0.010	0.020	0.25	0.51
L	0.016	0.050	0.41	1.27
L2	0.010 BSC	0.25 BSC	----	----
M	0°	8°	0°	8°

### SOLDERING FOOTPRINT



### GENERIC MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QSOP20	PAGE 1 OF 2

